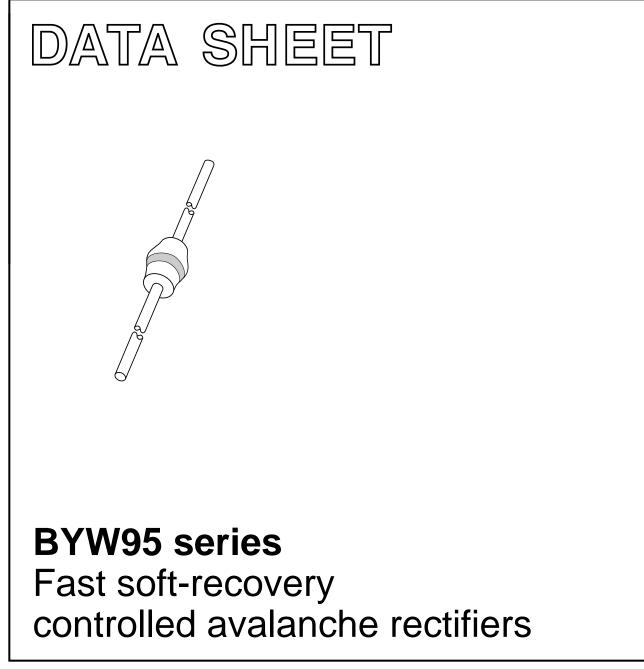
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of December 1979 File under Discrete Semiconductors, SC01 1996 Jun 07



Philips Semiconductors

BYW95 series

Fast soft-recovery controlled avalanche rectifiers

FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack
- Also available with preformed leads for easy insertion.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage				
	BYW95A		_	200	V
	BYW95B		_	400	V
	BYW95C		_	600	V
V _R	continuous reverse voltage				
	BYW95A		_	200	V
	BYW95B		_	400	V
	BYW95C		_	600	V
I _{F(AV)}	average forward current	$T_{tp} = 60 \text{ °C}$; lead length = 10 mm see Fig.2; averaged over any 20 ms period; see also Fig.6	_	3.00	A
		T _{amb} = 65 °C; PCB mounting (see Fig.11); see Fig.3; averaged over any 20 ms period; see also Fig.6	_	1.25	A
I _{FRM}	repetitive peak forward current	T _{tp} = 60 °C; see Fig.4	-	30	A
		T _{amb} = 65 °C; see Fig.5	_	13	A
I _{FSM}	non-repetitive peak forward current			70	A
E _{RSM}	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j \text{ max}}$ prior to surge; inductive load switched off		10	mJ
T _{stg}	storage temperature		-65	+175	°C
T _i	junction temperature	see Fig.7	-65	+175	°C

DESCRIPTION

Rugged glass SOD64 package, using a high temperature alloyed

construction. This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

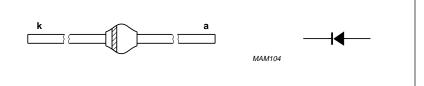


Fig.1 Simplified outline (SOD64) and symbol.

Fast soft-recovery controlled avalanche rectifiers

BYW95 series

ELECTRICAL CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	forward voltage	$I_F = 5 \text{ A}; T_j = T_{j \text{ max}}; \text{ see Fig.8}$	_	_	1.25	V
		I _F = 5 A; see Fig.8	_	_	1.50	V
V _{(BR)R}	reverse avalanche breakdown voltage	I _R = 0.1 mA				
	BYW95A		300	_	-	V
	BYW95B		500	_	-	V
	BYW95C		700	_	-	V
I _R	reverse current	V _R = V _{RRMmax} ; see Fig.9	-	-	1	μA
		V _R = V _{RRMmax} ; T _j = 165 °C; see Fig.9	-	-	150	μA
t _{rr}	reverse recovery time	when switched from $I_F = 0.5 A$ to $I_R = 1 A$; measured at $I_R = 0.25 A$; see Fig.12	_	_	250	ns
C _d	diode capacitance	$f = 1 \text{ MHz}; V_R = 0 \text{ V}; \text{ see Fig.10}$	_	85	_	pF
dI _R dt	maximum slope of reverse recovery current	when switched from I_F = 1 A to $V_R \ge 30$ V and dI_F/dt = -1 A/µs; see Fig.13	-	-	7	A/μs

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	75	K/W

Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.11. For more information please refer to the *'General Part of Handbook SC01.'*

Product specification

BYW95 series

GRAPHICAL DATA

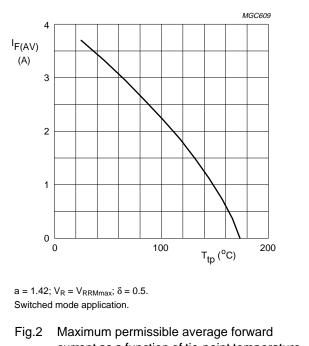
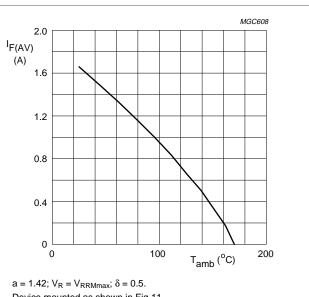


Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).



Device mounted as shown in Fig.11. Switched mode application.

Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

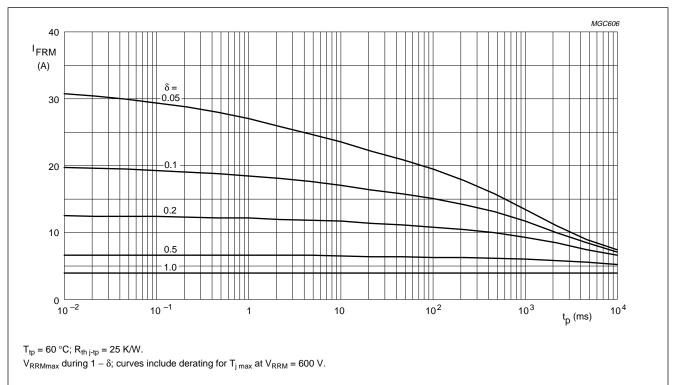


Fig.4 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

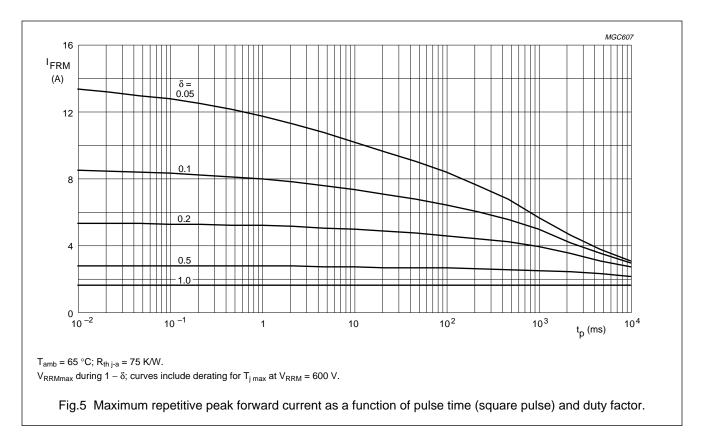
Fast soft-recovery controlled avalanche rectifiers

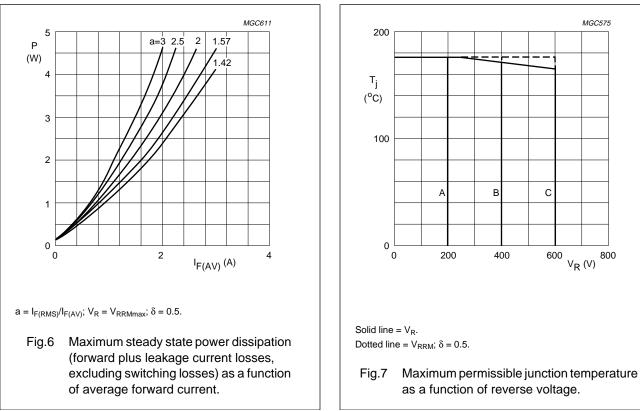
BYW95 series

MGC575

800

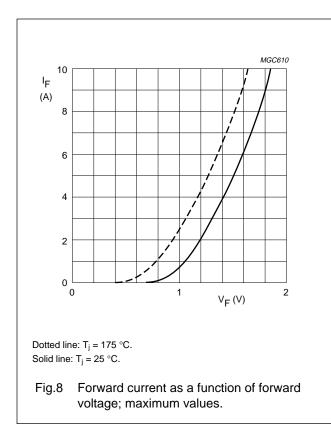
V_R (V)

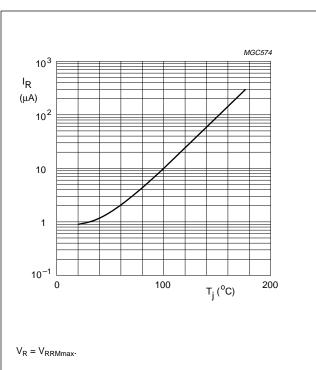


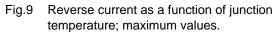


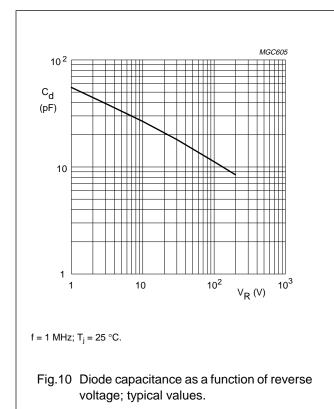
Fast soft-recovery controlled avalanche rectifiers

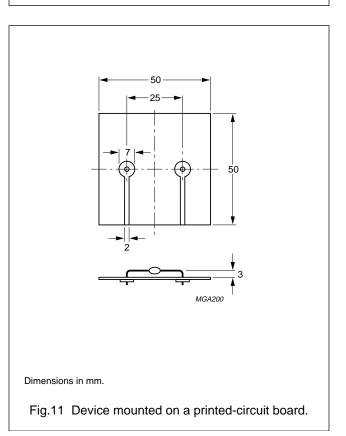
BYW95 series





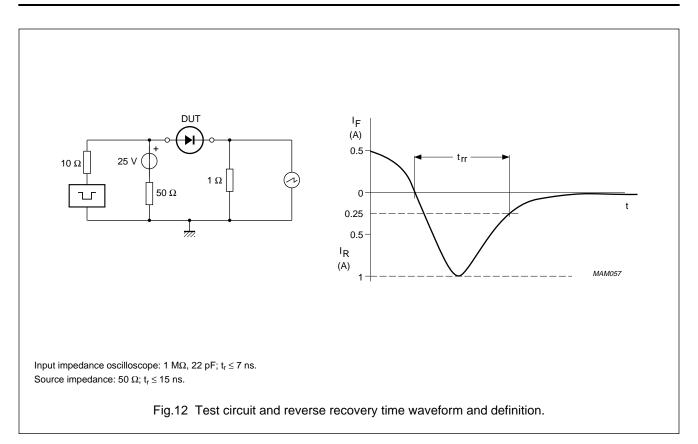


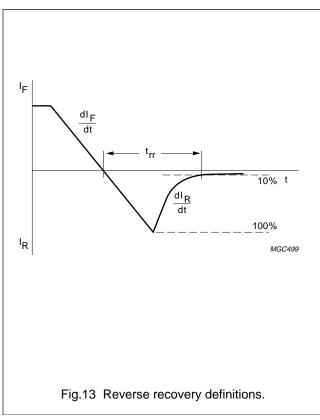




Fast soft-recovery controlled avalanche rectifiers

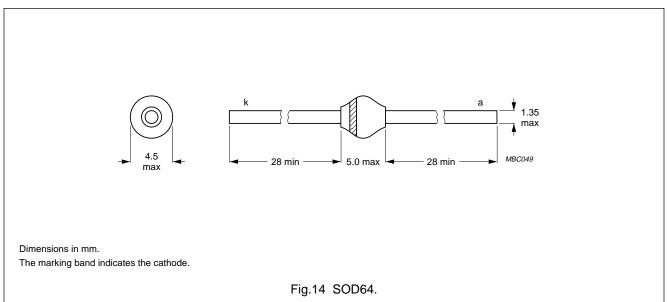
BYW95 series





BYW95 series

PACKAGE OUTLINE



DEFINITIONS

Data Sheet Status		
Objective specification	tive specification This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
more of the limiting values m of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or hay cause permanent damage to the device. These are stress ratings only and operation ny other conditions above those given in the Characteristics sections of the specification miting values for extended periods may affect device reliability.	
Application information		
Where application information	n is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.